

Preliminary Amendment
Application No.: filed concurrently
April 19, 2005

IN THE CLAIMS

Please substitute the following claims for the pending claims with the same numbers respectively:

Claim 1 (Original): A lead-free solder, which contains zinc and tin, and also contains 5 weight percent or less nickel with a liquid phase temperature of 260°C or greater.

Claim 2 (Currently amended): ~~[[A]] The lead-free solder, which has a liquid phase temperature of 260°C or greater, and contains according to claim 1, wherein said zinc content is 30 to 70 weight percent zinc, 5 weight percent or less nickel, and the remaining weight percent tin.~~

Claim 3 (Currently amended): ~~[[A]] The lead-free solder, which contains zinc and tin, and also contains 5 weight percent or less nickel and according to claim 1, wherein said solder further containing 0.5 weight percent or less aluminum with a liquid phase temperature of 260°C or greater.~~

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Claim 4 (Original): A lead-free solder, which contains zinc and tin, and also contains 1 weight percent or less copper with a liquid phase temperature of 260°C or greater.

Claim 5 (Original): A lead-free solder containing zinc and tin, wherein the content ratio of said zinc and tin is set so that the temperature difference between a solid phase temperature and a liquid phase temperature is at least 60°C.

Claim 6 (Original): A lead-free joint, which contains zinc and tin, and also contains 5 weight percent or less nickel.

Claim 7 (Original): The lead-free joint according to claim 6, wherein said joint is used in copper connections.

Claim 8 (Currently amended): [[A]] The lead-free joint,
~~which contains according to claim 6, wherein said zinc content is~~
~~30 to 70 weight percent zinc, 5 weight percent or less nickel,~~
~~and the remaining weight percent tin.~~

Claim 9 (Original): The lead-free joint according to claim 8, wherein said joint is used in copper connections.

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Claim 10 (Currently amended): [[A]] The lead-free joint,
~~which contains zinc and tin, and also contains 5 weight percent~~
~~or less nickel and~~ according to claim 6, wherein said joint
further containing 0.5 weight percent or less aluminum.

Claim 11 (Original): The lead-free joint according to claim
10, wherein said joint is used in copper connections.

Claim 12 (Original): A lead-free joint containing zinc and
tin, wherein the content ratio of said zinc and tin is set so
that the temperature difference between a solid phase temperature
and a liquid phase temperature is at least 60°C.

Claim 13 (Original): The lead-free joint according to claim
12, wherein said joint is used in copper connections.